STACK INFORMATION

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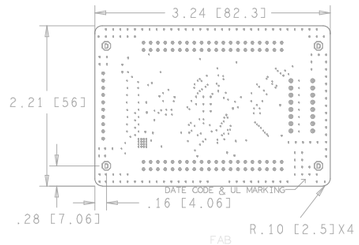
LAYERS	TYPE	THICKNESS(MILS)					
		TOP SIDE SOLDER MASK	0.50MILS	SINGLE ENDED	OHM	DIFFERENTIAL	OHM
L1	TOP	COPPER+PLATING	1.40MILS	10 MILS,50 OHM+/-10%	51.19 OHM		
		PREPREG	6.00 MILS				
L2	PWR1	COPPER	1.40MILS				
		CORE	44.0MILS				
L3	GND1	COPPER	1.40MILS				
		PREPREG	6.00MILS				
L4	BOTTOM	COPPER	1.40MILS	10 MILS,50 OHM +/-10%	51.19 OHM		
		BOTTOM SIDE SOLDER MASK	0.50 MILS	BOARD THICKNESS : 0.062" +/-0.006",MATERIAL 370HR			
		TOTAL	62.60 MILS				
			1.59MM				

DRILL CHART: TOP to BOTTOM ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
·	10.0	+3.0/-3.0	PLATED	139
·	12.0	+3.0/-3.0	PLATED	166
•	31.65	+3.0/-3.0	PLATED	16
•	40.0	+3.0/-3.0	PLATED	90
◎	118.0	+2.0/-2.0	NON-PLATED	4



REVISIONS			
REV	DESCRIPTION	DATE	APPROVED

NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED
2. MATERIAL:
   A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM.
   C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION
3. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 TOL.
      UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
      COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE
      BOARD OR BOTH SIDES IF APPLICABLE.
   B.FABRICATOR TO PLACE DATE CODE AND UL LOGO ON SECONDARY SIDE IN SILKSCREEN
6. FINAL FABRICATION:
   A. SOLDERMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE
      MASK MATERIAL OVER BARE COPPER..PER IPC-SM-840. MASK ARTWORKS PROVIDED
      ARE 1:1. SOLDERMASK COLOR **BLUE**
   B. ALL VIAS THAT ARE PLACED ON EXPOSED PADS MUST BE PLUGGED WITH SOLDERMASK INK ON THE SIDE
      WHERE IT IS MASKED IN THE SOLDER MASK FILM.THIS IS TO AVOID SOLDER FLOW THROUGH VIA HOLE.
7. FINISH:
   A. SHALL BE ELECTROLYTIC NICKEL/GOLD. ELECTROLESS NIKEL / IMMERSION GOLD. (ENIG)
   B. NICKEL THICKNESS, 100-200 MICROINCHES.
   C. GOLD THICKNESS; 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY AND SHALL BE
   MARKED IN SILKSCREEN ON SECONDARY SIDE OF BOARD WITH VENDORS UL IDENT.
   FLAMABILITY RATING (94-V), DATE CODE (WWYY), AND RoHS COMPLIANT SYMBOL.
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD
   IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WARP OR TWIST SHALL NOT EXCEED 0.005" PER INCH
11. TESTING:
   A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED
   B. T-LINE IMPEDANCE TO BE TESTED OR GURANTEED WITHIN 10% IF SPECIFIED IN
      THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED
12. MINIMUM TRACE WIDTH : 8 MILS
    MINIMUM SPACING : 8 MILS
13. LAYER LADDER PROVIDED IN THE PCB SHOULD NOT BE MASKED
14. DESIGN TEAM:
      IN SOLDER MASK LAYER, COPPER PAD HAS BEEN ENABLED INSTEAD OF MASK PAD
      FOR PROVIDING 1:1 SOLDER MASK OPENING FOR PADS ALL OVER THE BOARD.
    CAM TEAM:
      PLS DELETE NOTE 14 DURING GERBER GENERATION

UNLESS OTHERWISE SPECIFIED	SIGNATURES		DATE
DIMENSIONS ARE IN INCHES TOLERANCES ON: ANGLES +/- 2 2 PL DECIMALS +/- .010 3 PL DECIMALS +/- .005 THIRD ANGLE PROJECTIONS	DRAWN	: HUSAIN	27/08/14
	CHECKED	: PRAJITH	27/08/14
	ENGRG	: DHANRAJ	27/08/14
	ISSUED		

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FABRICATION DRAWING
CYUSB3ACC-007
CPLD ACCESSORY BOARD

SIZE	FSCM NO	DWG NO	REV
C		610-60210-01	02

SCALE: 1/1 SHEET 1 OF 1